# Product / Process Change Notification



N° 2013-065-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

### Infineon goes Green: Implementation of a Green version (RoHS and WEEE compliant) for Infineon Profet™ products

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 28. April 2014.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

#### Disclaimer:

If we do not receive any response by the date in the PCN above we consider this as the acceptance of the PCN. After the last order date as stated herein, purchase orders related to the unchanged product(s) cannot be accepted.

In case the customer rejects this PCN this PCN shall be considered a product discontinuation notice (PD).

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### **Product / Process Change Notification**



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**SUBJECT OF CHANGE:** Implementation of a Green version (RoHS and WEEE compliant) for

Infineon Profet™ products. Transfer of PROFET<sup>TM</sup> products from

conventional to LPL assembly line

PRODUCTS AFFECTED: See 1\_cip13065

**REASON OF CHANGE:** The products are converted to a green, RoHS, and WEEE compliant

version in order to meet market requirements. In order to secure supply Infineon needs to transfer to a new assembly line (called LPL

assembly line).

DESCRIPTION OF CHANGE:	<u>OLD</u>	<u>NEW</u>
■ Package name	P-TO220-7-128 (SMD) P-TO220-5-62 (SMD)	PG-TO263-7-2 (SMD) PG-TO263-5-2 (SMD)
■ Package dimensions	see customer information package 3_cip13065	
■ plating at outer leads	PbSn	Sn
■ moisture level	MSL1 @220°C	MSL 3 @245°C
■ Data Sheet	old package name old package drawing old SP number	new package name new package drawing new SP number

#### **PRODUCT IDENTIFICATION:** • On Packing level:

o Package name

o SP number

On datasheet level:

Package drawing

o Package name

SP number

#### TIME SCHEDULE:

■ Final qualification report:	available
■ First samples available:	available
■ Start of delivery:	15-July-2014 or earlier on request
■ Last order date of unchanged product:	15-July-2014
Last delivery date of unchanged product:	31-December-2014

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**ASSESSMENT:** 

- Products are compatible to lead-free and lead-containing board assembly processes.
- Positive results from: visual inspection, solderability test, tin thickness, lead content check, whisker assessment
- Continuously SPC monitoring of solderability and tin thickness
- No impact on parameters and reliability proven via technology and product qualification. Processes are optimized to meet product performance according to specification.

**REMARK:** Please take care of the product discontinuation PD\_017\_14

**DOCUMENTATION:** 1\_cip13065 Product list

3\_cip13065 Customer information package

4\_cip13065 Data sheets

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